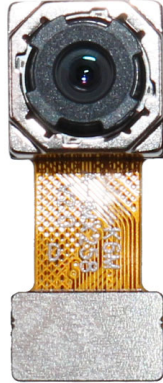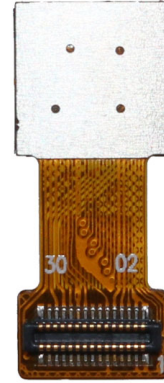## YDS-K6MA-IMX258 V2.0
13MP Sony IMX258 MIPI Interface Auto Focus Camera Module

Front View

Back View

Specifications

| Camera Module No.	YDS-K6MA-IMX258 V2.0
Resolution	13MP
Image Sensor	IMX258
Sensor Type	1/3.06"
Pixel Size	1.12 um x 1.12 um
EFL	2.35 mm
F.NO	2.40
Pixel	4224 x 3136
View Angle	127.0°(DFOV) 99.5°(HFOV) 70.0°(VFOV)
Lens Dimensions	8.50 x 8.50 x 6.45 mm
Module Size	20.85 x 8.50 mm
Module Type	Auto Focus
Interface	MIPI
Auto Focus VCM Driver IC	DW9763
Lens Model	YDS-LENS-TK1267
Lens Type	650nm IR Cut
Operating Temperature	-20°C to +70°C
Mating Connector	BBR43-30KB533

YDS-K6MA-IMX258 V2.0
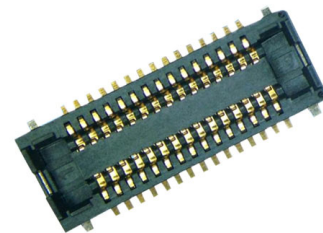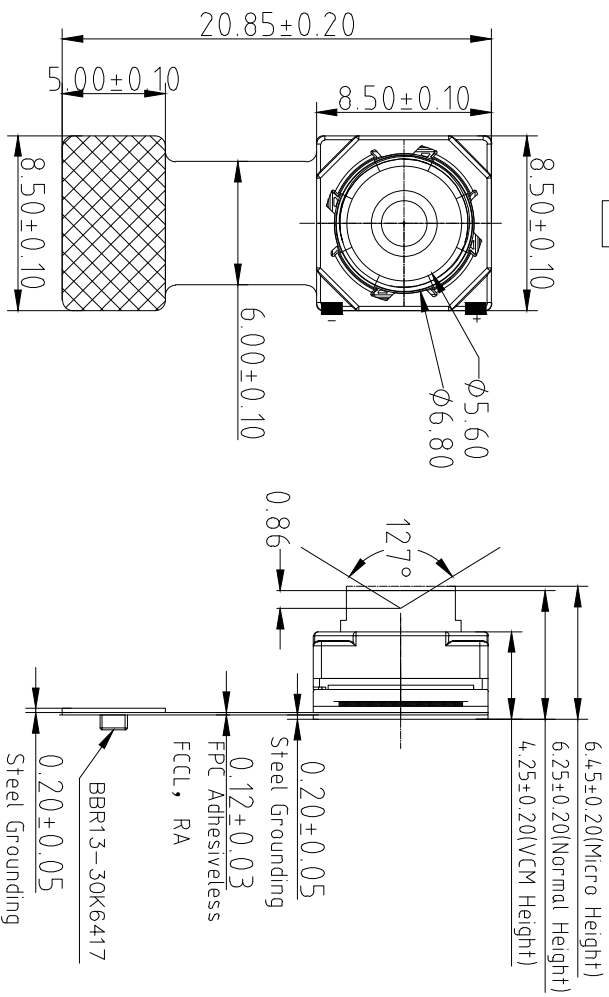## 13MP Sony IMX258 MIPI Interface Auto Focus Camera Module
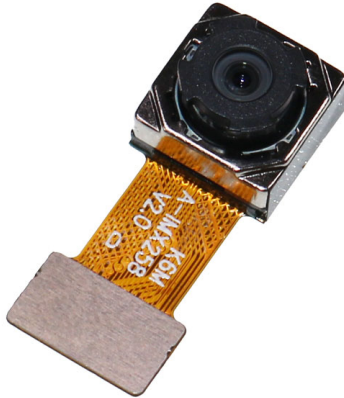
Top View

Side View
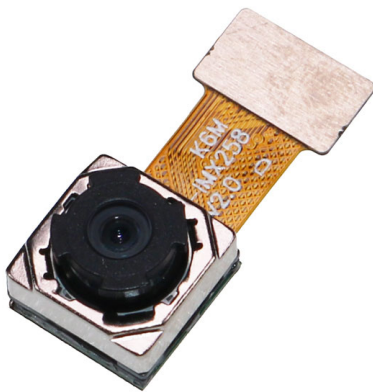
Bottom View

Mating Connector

RoHS

	SIGNAL
0	SIGNAL
1	GND
2	GND
3	GND
4	GND
5	AFVDD2.8V
6	AFEN
7	SDA
8	DOVDD1.8V
9	SCL
10	DVDD1.2V
11	GND
12	XSHUTDOWN
13	MCN
14	NC
15	MCP
16	GND
17	MD0N
18	MCLK
19	MD0P
20	GND
21	MD1N
22	FLASH
23	MD1P
24	AVDD2.8V
25	VPP(NC)
26	AGND
27	MD2N
28	MD3N
29	MD2P
30	MD3P

Parameters:

1、Sensor specification:

Image Sensor: IMX258
Pixel: 1.12um×1.12um
Lens Type: 1/3.06

Important Voltage Description: DVDD1.2V
(external power supply);

2、Lens specification:

FOV: 127°(D),99.5°(H),70°(V)
F/NO: 2.4
TV distortion: <-10.5%
Focal length: 2.35mm
Composition: 6P+IR FILTER
IR Cut Coating: 650nm±10nm@50%

TOP VIEW

20.85±0.20
5.00±0.10
8.50±0.10
8.50±0.10
6.00±0.10
φ5.60
φ6.80

SIDE VIEW

0.86
127°
6.45±0.20(Micro Height)
6.25±0.20(Normal Height)
4.25±0.20(VCM Height)
0.20±0.05
Steel Grounding
0.12±0.03
FPC Adhesiveless
FCCL, RA
BBR13-30k6417
0.20±0.05
Steel Grounding

BOTTOM VIEW

4.25
2.50
29
30
2
1

NOTE:
1.The device slave address:0x34;
2.Driver IC and its I2C Address:
DW9763; 0x18h;

Version	Information	Date
V1.0	First Version	5-23-2019
V2.P	Change lens and VCM	5-20-2020

Designed By	Kevin	
Checked By	Aouly_Yan	

Model Name:	K6MA-IMX258 V2.0

Projection Type: Third Angle
Unit: mm
Material:
Scale: 1:1
Sheet: 1 of 1
Version: 1/0

SONY

[Product Brief]

Ver.1.0

IMX258

Diagonal 5.867 mm (Type 1/3.06) 13Mega-Pixel CMOS Image Sensor with Square Pixel for Color Cameras

Description

IMX258 is a diagonal 5.867mm (Type 1/3.06) 13 Mega-pixel CMOS active pixel type stacked image sensor with a square pixel array. It adopts Exmor RS™ technology to achieve high speed image capturing by column parallel A/D converter circuits and high sensitivity and low noise image (comparing with conventional CMOS image sensor) through the backside illuminated imaging pixel structure. R, G, and B pigment primary color mosaic filter is employed. By introducing spatially multiplexed exposure technology, high dynamic range still pictures and movies are achievable. It
equips an electronic shutter with variable integration time. It operates with three power supply voltages: analog 2.7 V, digital 1.2 V and 1.8 V for input/output interface and achieves low power consumption.
In addition, this product is designed for use in cellular phone and tablet pc. When using this for another application, Sony does not guarantee the quality and reliability of product. Therefore, don't use this for applications other than cellular phone and tablet pc. Consult your Sony sales representative if you have any questions.

Functions and Features

◆ Back-illuminated and stacked CMOS image sensor Exmor RSTM

◆ Phase Detection pixel data output for Phase Detection Auto Focus

◆ High Dynamic Range (HDR) mode with raw data output.

◆ High signal to noise ratio (SNR).

◆ Full resolution @30fps (Normal / HDR). 4K2K @30fps (Normal / HDR) 1080p @60fps (Normal)

◆ Output video format of RAW10/8.

◆ Pixel binning readout and V sub-sampling function.

◆ Independent flipping and mirroring.

◆ CSI-2 serial data output (MIPI 2lane/4lane, Max. 1.3Gbps/lane, D-PHY spec. ver. 1.1 compliant)

◆ 2-wire serial communication.

◆ Two PLLs for independent clock generation for pixel control and data output interface.

◆ Dynamic Defect Pixel Correction.

◆ Fast mode transition. (on the fly)

◆ Dual sensor synchronization operation.

◆ 4K bit of OTP ROM for users.

◆ Built-in temperature sensor.

Device Structure

- ◆ CMOS image sensor
- ◆ Image size :   Diagonal 5.867 mm (Type 1/3.06)
- ◆ Total number of pixels :   4224 (H) × 3192 (V) approx. 13.48 M pixels
- ◆ Number of effective pixels :   4224 (H) × 3144 (V) approx. 13.28 M pixels
- ◆ Number of active pixels :   4208 (H) × 3120 (V) approx. 13.13 M pixels
- ◆ Chip size :   5.990 mm (H) × 3.908 mm (V)
- ◆ Unit cell size :   1.12 μm (H) × 1.12 μm (V)
- ◆ Substrate material :   Silicon

System block diagram
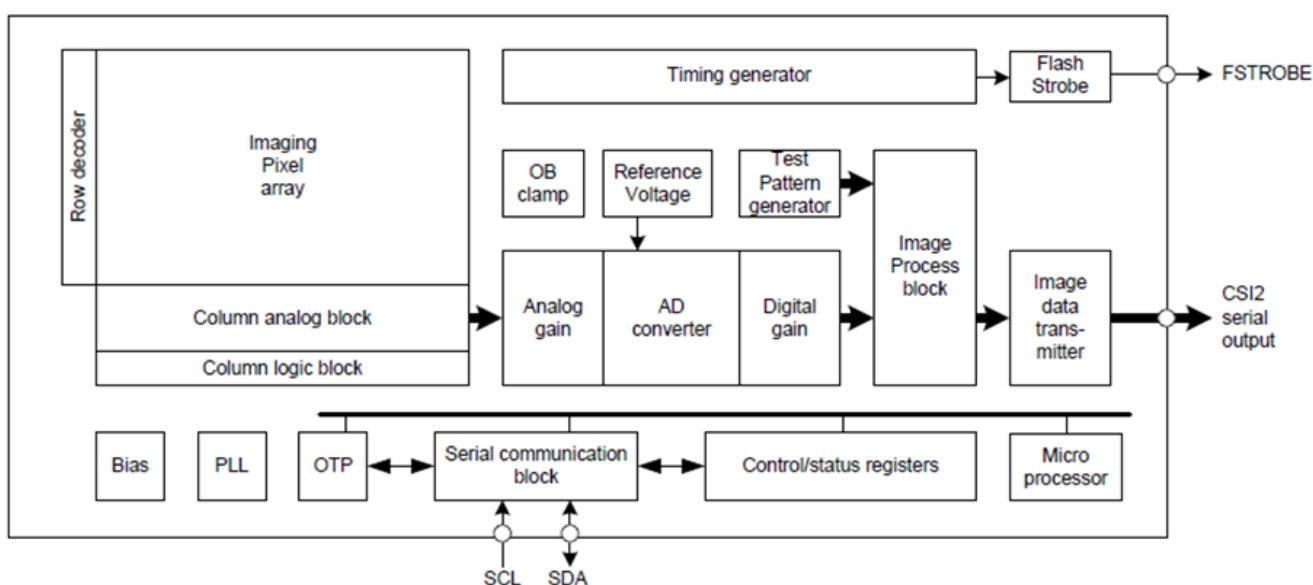
Exmor RS

* Exmor RS is a trademark of Sony Corporation. The Exmor RS is a Sony's CMOS image sensor with high-resolution, high-performance and compact size by replacing a supporting substrate in Exmor R™ which changed fundamental structure of Exmor™ pixel adopted column parallel A/D converter to back-illuminated type, with layered chips formed signal processing circuits.

1. General Description

The DW9763 is a single 10-bit DAC with 100mA output current sinking capability and embedded 8KByte eFlash memory. Designed for linear control of voice coil motors, the DW9763 is capable of operating voltage up to 3.3V.

The SAC (Smart Actuator Control) mode is applied to minimize the mechanical vibration. The SAC mode highly improves the actuator's settling time and tolerance coverage compared with conventional LSC (Linear Slope Control) mode. The DAC and eFlash are controlled via an I2C compatible serial interface.

The DW9763 incorporates with a POR (Power On Reset) circuit, power down mode. POR circuit gets to operate when VDD (supply power) turns on. The output current keeps 0mA until valid register value takes place. During the power down mode, it consumes current max.1uA.

The DW9763 is designed for auto focus and optical zoom for mobile camera, digital still camera, camcorders and other nano actuator applications.
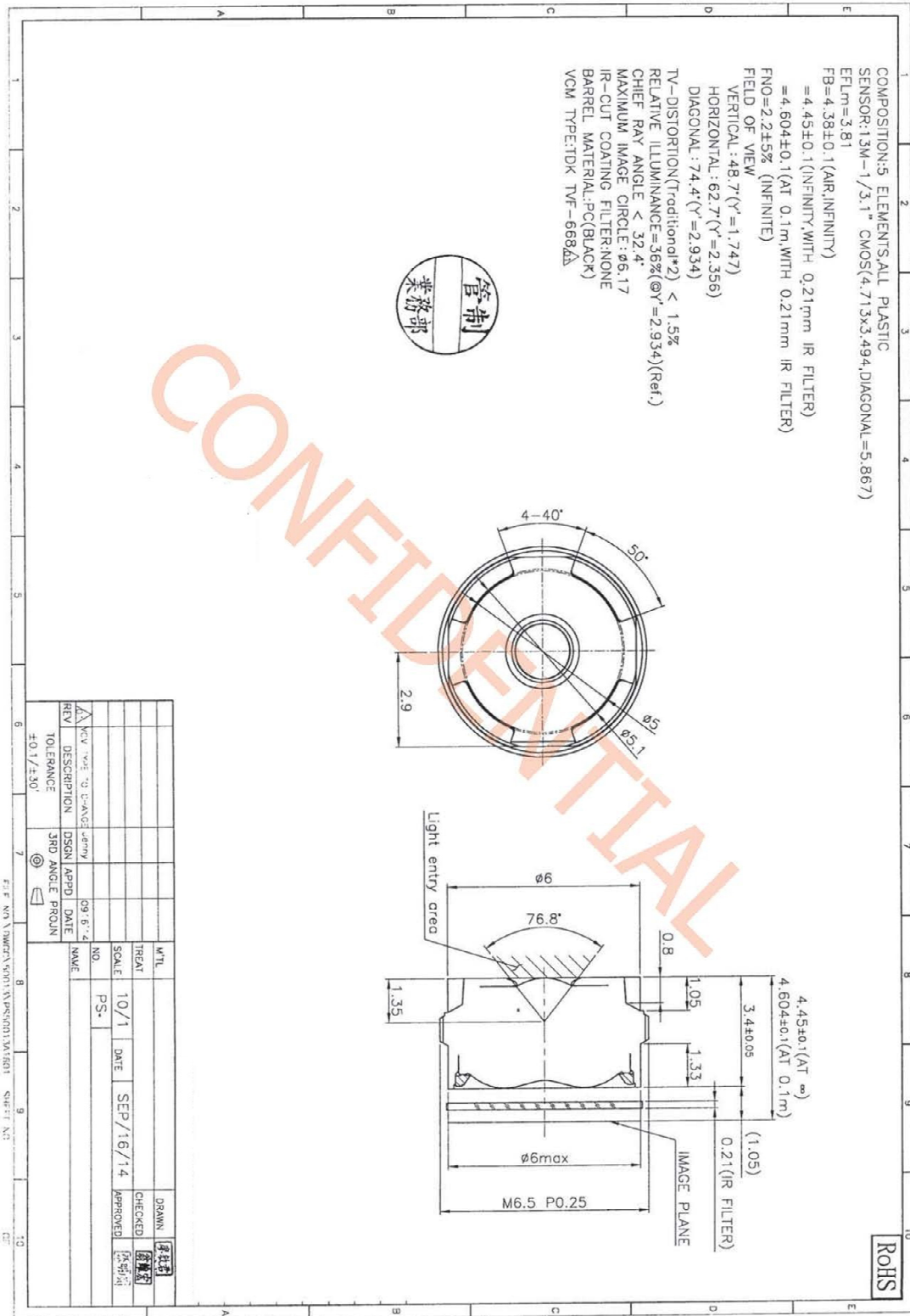
■ **Features**

10 bit resolution current sinking of 100mA for VCM
SAC (Smart Actuator Control) mode
Supply voltage range (VDD) : 2.3V to 3.3V
Fast mode I2C interface compatible (1.8V interface available)
Power down mode
Power on reset (POR)
Embedded 8KByte eFlash memory
Package : 8 pin WLCSP
Package Size : 0.77mm X 1.75mm X 0.3mm

■ **Applications**

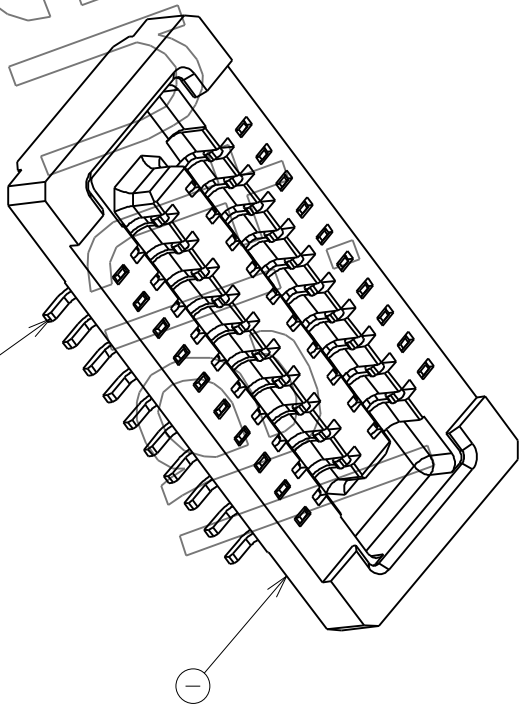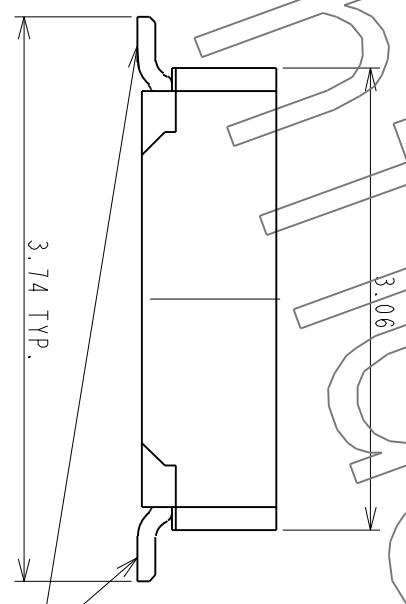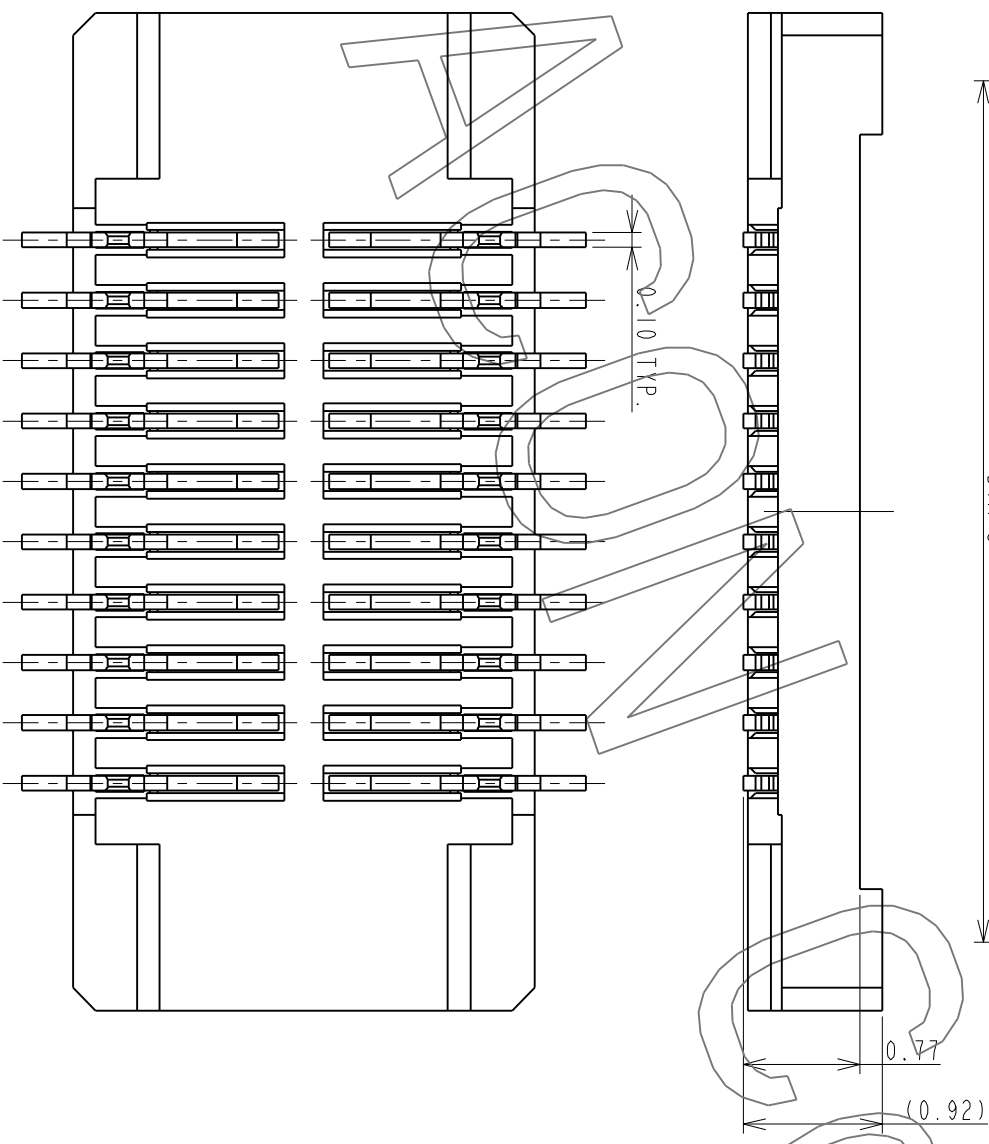Mobile camera
Digital still camera
Camcorder
Web camera
Nano actuator

COMPOSITION:5 ELEMENTS,ALL PLASTIC
SENSOR:13M~1/3.1" CMOS(4.713x3.494,DIAGONAL=5.867)
EFLm=3.81
FB=4.38±0.1(AIR,INFINITY)
=4.45±0.1(INFINITY,WITH 0.21mm IR FILTER)
=4.604±0.1(AT 0.1m,WITH 0.21mm IR FILTER)
FNO=2.2±5% (INFINITE)
FIELD OF VIEW
VERTICAL:48.7°(Y'=1.747)
HORIZONTAL:62.7°(Y'=2.356)
DIAGONAL:74.4°(Y'=2.934)
TV-DISTORTION(Traditional*2) < 1.5%
RELATIVE ILLUMINANCE=36%(@Y'=2.934)(Ref.)
CHIEF RAY ANGLE < 32.4°
MAXIMUM IMAGE CIRCLE:φ6.17
IR-CUT COATING FILTER:NONE
BARREL MATERIAL:PC(BLACK)
VCM TYPE:TDK TVF-668

0.10 TYP.

0.40 TYP.

DIM A

DIM B

DIM C

0.77

(0.92)

3.74 TYP.

3.06

0.08

ALL OF PLACES

REV.	EC#	DESCRIPTION	DATE	DRAWN	CHECKED	APPROVED
A	TJECR10018-02	NEW RELEASE PER NPR10009	11/05/10'	RAIN	SteveM eng	Jeff
B	TJECR13014	X1,AX1	05/13/13'	RAIN		

CUSTOMER DRAWING

ITEM		NAME		PART #			
1		HOUSING		1-BBR43-100X30			
2		CONTACT		1-BBR43-1XXX33			

	NAME	DATE
DRAWN	RAIN	04/15/10'
DESIGN	RAIN	04/15/10'
CHECKED	RAIN	04/15/10'
HARDWARE	DICK.LEE	04/24/10'
APPROVED	DICK.LEE	04/24/10'

TOLERANCES UNLESS OTHERWISE SPECIFIED
GENERAL X. ±0.38
.Xx ±0.25
.XXX ±0.13
.XXXX ±0.05

ANGLES X° ±3.0°
.X° ±2.0°
.XX° ±1.0°

TITLE
P0.4*H1.0mm BOARD TO BOARD
CONN RECEPTACLE
WITHOUT HOLD DOWN
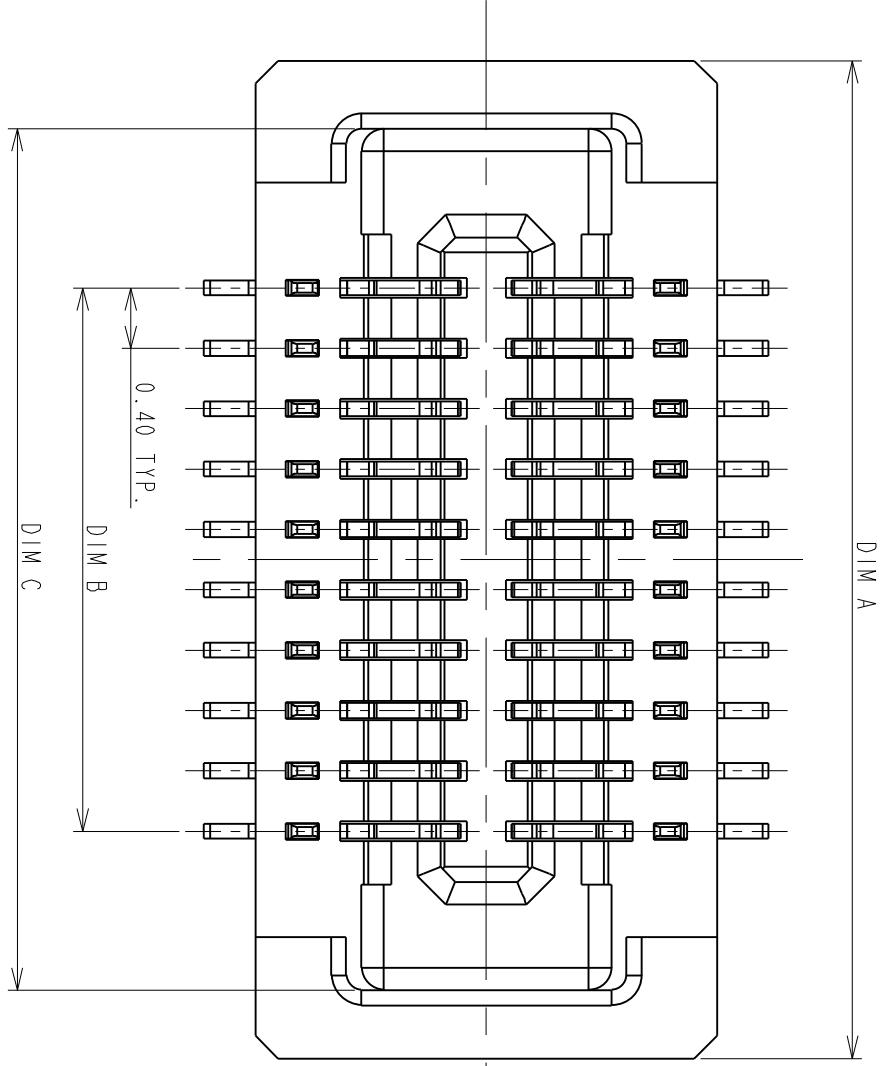
MATERIAL / FINISH
COPPER ALLOY/PLATING GOLD
HIGH TEMP RESIN/UL 94 V-0

SCALE 20:1
SHEET 1 OF 2
UNIT mm

SERIES BBR

DWG NO. C-BBR43-04-01

SIZE A3
REV. B
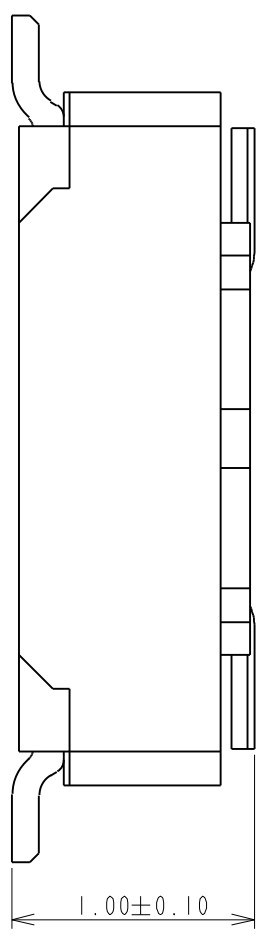
PRODUCT NUMBERING CODE:

BBR43 - XX   K   X   5   X   X
   1   2   3   4   5   6   7

1.PRODUCTION CODE:
   BBR43:BOARD TO BOARD 0.4 PITCH RECEPTACLE
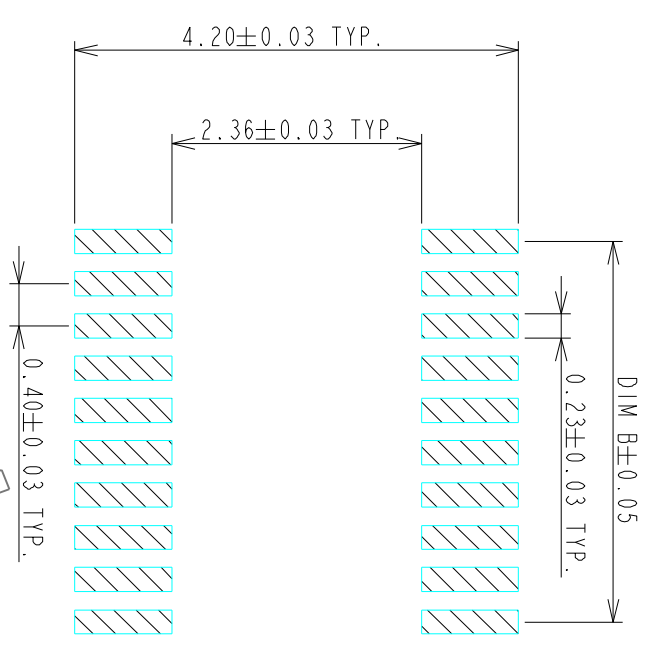
2.POSITIONS:
   XX: POSITIONS(SEE TABLE A)

3.INSULATOR COLOR:
   K: BLACK

4.CONTACT PLATING:
   1:GOLD 1u" MIN
   2:GOLD 5u" MIN
   3:GOLD 10u" MIN
   B:GOLD 4u" MIN FOR SPOT PLATING
   ALL OVER Ni 50~100u"

5.TYPE OF HEIGHT:
   5: H=0.77mm

6. TYPE OF HOLD DOWN:
   3: WITHOUT HOLD DOWN

7.OTHER
   2: WITH POST,FINISHED PRODUCTS
   3: WITHOUT POST,FINISHED PRODUCTS

1.00±0.10

RECOMMENDED P.C.BOARD PATTERN DIMENSION (WITHOUT HOLD DOWN)

4.20±0.03 TYP.
2.36±0.03 TYP
0.40±0.03 TYP.
0.23±0.03 TYP.
DIM B±0.05

NOTES:
1.0: RATING:
   1.1: VOLTAGE:60V AC/DC
   1.2: CURRENT:0.5 AMPS
   1.3: OPERATION TEMPERATURE:-40°C TO +85°C
2.0: ELECTRICAL CHARACTERISTIC:
   2.1: CONTACT RESISTANCE: 50 mΩ MAX INITIAL
   2.2: INSULATION RESISTANCE: 1000 MΩ MIN INITIAL
   2.3: DIELECTIC WITHSTANDING VOLTAGE: 250V AC FOR ONE MINUTE
3.0 TOLERANCES UNLESS OTHERWISE SPECIFIED
   GENERAL:
      DIMENSION >10.00   ±0.13
      DIMENSION 5.00~10.00   ±0.10
      DIMENSION <5.00   ±0.05
   ⚠ 4.0 ALL COPLANARITY IS 0.08mm MAX.BEFORE REFLOW
      ALL COPLANARITY IS 0.10mm MAX.AFTER REFLOW

TABLE A:

POSITIONS	DIM A	DIM B	DIM C
10	4.61	1.60	3.71
14	2.40	2.40	4.51
16	5.41	2.80	4.91
18	6.21	3.20	5.31
20	6.61	3.60	5.71
22	7.01	4.00	6.11
24	7.41	4.40	6.51
26	7.81	4.80	6.91
30	8.61	5.60	7.71
32	9.01	6.00	8.11
34	9.41	6.40	8.51
40	10.61	7.60	9.71
44	11.41	8.4	10.51
48	12.21	9.20	11.31
50	12.61	9.60	11.71
54	13.41	10.40	12.51
60	14.61	11.60	13.71
70	16.61	13.60	15.71
80	18.61	15.60	17.71

Camera Module Pinout Definition Reference Chart

OmniVision Sony Samsung On-Semi Aptina Himax GalaxyCore PixArt SmartSens Sensors	
Pin Signal	**Description**
DGND GND	ground for digital circuit
AGND	ground for analog circuit
PCLK DCK	DVP PCLK output
XCLR PWDN XSHUTDOWN STANDBY	power down active high with internal pull-down resistor
MCLK XVCLK XCLK INCK	system input clock
RESET RST	reset active low with internal pull-up resistor
NC NULL	no connect
SDA SIO_D SIOD	SCCB data
SCL SIO_C SIOC	SCCB input clock
VSYNC XVS FSYNC	DVP VSYNC output
HREF XHS	DVP HREF output
DOVDD	power for I/O circuit
AFVDD	power for VCM circuit
AVDD	power for analog circuit
DVDD	power for digital circuit
STROBE FSTROBE	strobe output
FSIN	synchronize the VSYNC signal from the other sensor
SID	SCCB last bit ID input
ILPWM	mechanical shutter output indicator
FREX	frame exposure / mechanical shutter
GPIO	general purpose inputs
SLASEL	I2C slave address select
AFEN	CEN chip enable active high on VCM driver IC
MIPI Interface	
MDN0 DN0 MD0N DATA_N DMO1N	MIPI 1st data lane negative output
MDP0 DP0 MD0P DATA_P DMO1P	MIPI 1st data lane positive output
MDN1 DN1 MD1N DATA2_N DMO2N	MIPI 2nd data lane negative output
MDP1 DP1 MD1P DATA2_P DMO2P	MIPI 2nd data lane positive output
MDN2 DN2 MD2N DATA3_N DMO3N	MIPI 3rd data lane negative output
MDP2 DP2 MD2P DATA3_P DMO3P	MIPI 3rd data lane positive output
MDN3 DN3 MD3N DATA4_N DMO4N	MIPI 4th data lane negative output
MDP3 DP3 MD3P DATA4_P DMO4P	MIPI 4th data lane positive output
MCN CLKN CLK_N DCKN	MIPI clock negative output
MCP CLKP MCP CLK_P DCKN	MIPI clock positive output
DVP Parallel Interface	
D0 DO0 Y0	DVP data output port 0
D1 DO1 Y1	DVP data output port 1
D2 DO2 Y2	DVP data output port 2
D3 DO3 Y3	DVP data output port 3
D4 DO4 Y4	DVP data output port 4
D5 DO5 Y5	DVP data output port 5
D6 DO6 Y6	DVP data output port 6
D7 DO7 Y7	DVP data output port 7
D8 DO8 Y8	DVP data output port 8
D9 DO9 Y9	DVP data output port 9
D10 DO10 Y10	DVP data output port 10
D11 DO11 Y11	DVP data output port 11

Cameras Applications

Camera Reliability Test

Reliability Inspection Item		Testing Method	Acceptance Criteria
Category	Item		
Environmental	Storage Temperature — High 60°C 96 Hours	Temperature Chamber	No Abnormal Situation
	Storage Temperature — Low -20°C 96 Hours	Temperature Chamber	No Abnormal Situation
	Operation Temperature — High 60°C 24 Hours	Temperature Chamber	No Abnormal Situation
	Operation Temperature — Low -20°C 24 Hours	Temperature Chamber	No Abnormal Situation
	Humidity — 60°C 80% 24 Hours	Temperature Chamber	No Abnormal Situation
	Thermal Shock — High 60°C 0.5 Hours / Low -20°C 0.5 Hours / Cycling in 24 Hours	Temperature Chamber	No Abnormal Situation
Physical	Drop Test (Free Falling) — Without Package 60cm	10 Times on Wood Floor	Electrically Functional
	Drop Test (Free Falling) — With Package 60cm	10 Times on Wood Floor	Electrically Functional
	Vibration Test — 50Hz X-Axis 2mm 30min	Vibration Table	Electrically Functional
	Vibration Test — 50Hz Y-Axis 2mm 30min	Vibration Table	Electrically Functional
	Vibration Test — 50Hz Z-Axis 2mm 30min	Vibration Table	Electrically Functional
	Cable Tensile Strength Test — Loading Weight 4 kg / 60 Seconds / Cycling in 24 Hours	Tensile Testing Machine	Electrically Functional
Electrical	ESD Test — Contact Discharge 2 KV	ESD Testing Machine	Electrically Functional
	ESD Test — Air Discharge 4 KV	ESD Testing Machine	Electrically Functional
	Aging Test — On/Off 30 Seconds / Cycling in 24 Hours	Power Switch	Electrically Functional
	USB Connector — On/Off 250 Times	Plug and Unplug	Electrically Functional

YDS CAMERA MODULE

Camera Inspection Standard

Inspection Item		Inspection Method	Standard of Inspection
Category	Item		
Appearance	FPC/ PCB — Color	The Naked Eye	Major Difference is Not Allowed.
	FPC/ PCB — Be Torn/Chopped	The Naked Eye	Copper Crack Exposure is Not Allowed.
	FPC/ PCB — Marking	The Naked Eye	Clear, Recognizable (Within 30cm Distance)
	Holder — Scratches	The Naked Eye	The Inside Crack Exposure is Not Allowed
	Holder — Gap	The Naked Eye	Meet the Height Standard
	Holder — Screw	The Naked Eye	Make Sure Screws Are Presented (If Any)
	Holder — Damage	The Naked Eye	The Inside Crack Exposure is Not Allowed
	Lens — Scratch	The Naked Eye	No Effect On Resolution Standard
	Lens — Contamination	The Naked Eye	No Effect On Resolution Standard
	Lens — Oil Film	The Naked Eye	No Effect On Resolution Standard
	Lens — Cover Tape	The Naked Eye	No Issue On Appearance.
Function	Image — No Communication	Test Board	Not Allowed
	Image — Bright Pixel	Black Board	Not Allowed In the Image Center
	Image — Dark Pixel	White board	Not Allowed In the Image Center
	Image — Blurry	The Naked Eye	Not Allowed
	Image — No Image	The Naked Eye	Not Allowed
	Image — Vertical Line	The Naked Eye	Not Allowed
	Image — Horizontal Line	The Naked Eye	Not Allowed
	Image — Light Leakage	The Naked Eye	Not Allowed
	Image — Blinking Image	The Naked Eye	Not Allowed
	Image — Bruise	Inspection Jig	Not Allowed
	Image — Resolution	Chart	Follows Outgoing Inspection Chart Standard
	Image — Color	The Naked Eye	No Issue
	Image — Noise	The Naked Eye	Not Allowed
	Image — Corner Dark	The Naked Eye	Less Than 100px By 100px
	Image — Color Resolution	The Naked Eye	No Issue
Dimension	Height	The Naked Eye	Follows Approval Data Sheet
	Width	The Naked Eye	Follows Approval Data Sheet
	Length	The Naked Eye	Follows Approval Data Sheet
	Overall	The Naked Eye	Follows Approval Data Sheet

YDS CAMERA MODULE

your best camera partner

YDSCAM Package Solutions
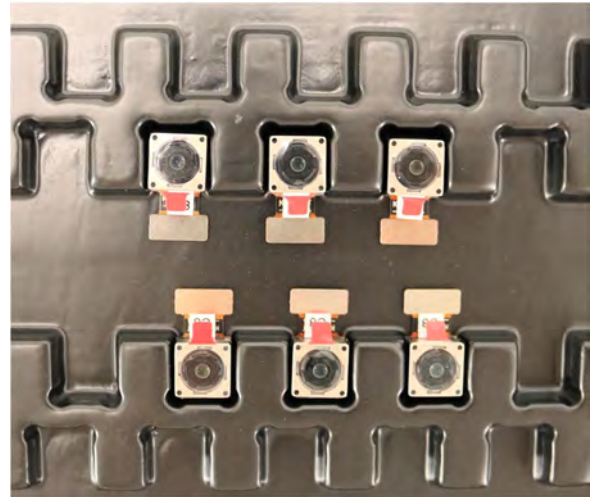
YDS Camera Module

Complete with Lens Protection Film

Tray with Grid and Space

Place Cameras on the Tray

YDSCAM Package Solutions

Full Tray of Cameras

Cover Tray with Lid

Place Tray into Anti-Static Bag

Vacuum the Anti-Static Bag

YDSCAM Package Solutions

Sealed Vacuum Anti-Static Bag with Labels

1. Model and Description   2. Quantity   3. Manufacturing Date Code 4. Caution

YDSCAM Package Solutions

Place Foam Sheets Between Tray Bags

Foam Sheets are Larger Than Trays

Place Foam Sheets and Trays into Box

Foam Sheets are Tightly Fitting in Box

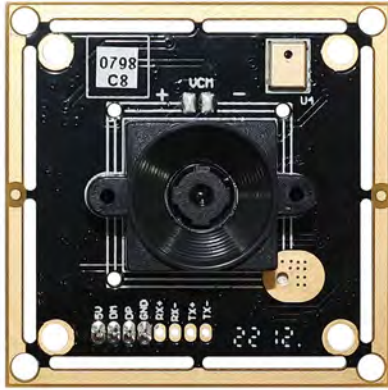Seal the Carbon Box

Label the Carbon Shipping Box

YDSCAM Package Solutions

USB Camera Module

Complete with Lens Protection Film

Place Camera Sample into Anti-Static Bag

Place USB Cameras into Tray

Seal the Tray with Anti-Static Bag

Label the Carbon Shipping Box

your best camera partner

YDSCAM Package Solutions

Place Camera Sample into Anti-Static Bag

Place Connectors into Anti-Static Bag

Label the Sample Bags

Place Connectors into Reel

Place Samples into the Carbon Box

Place Connectors into the Carbon Box

Company YDSCAM

YingDeShun Co. Ltd. (YDS) was established in 2017, a next-generation technology driven manufacturer specialized in research, design, and produce of audio and video products. YDS is occupying 20,000 square feet automated plants with 100 employees of annual throughput 30,000,000 units cameras.

YDS provides OEM, ODM design, contract manufacturing, and builds the camera products. You may provide the requirements to us, even with a hand draft, our sales and engineering work together to meet your needs. We consider ourselves your last-term partner in developing practical and innovative solutions.

Our team covers everything from initial concept development to mass produced product. YDS specializes in customized camera design, raw material, electronic engineering, firmware/software development, product testing, and packing design. Our experienced strategic supply systems offer a robust and dependable manufacturing capacity for orders of various sizes.

USB camera module
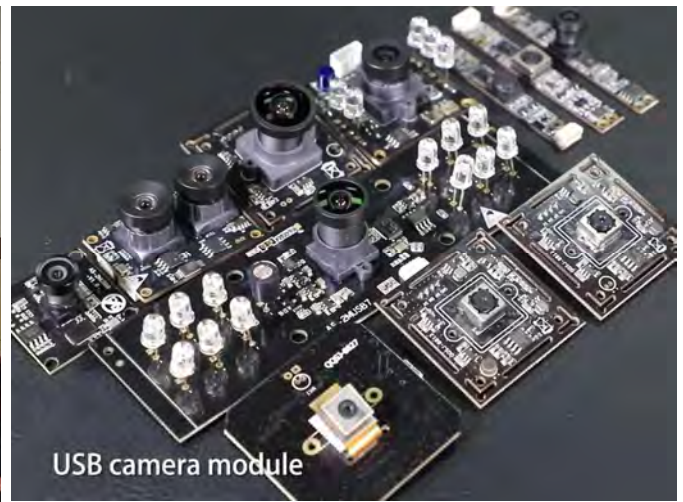
Limited Warranty

YDS provides the following limited warranty if you purchased the Product(s) directly from YDS company or from YDS's website www.YDSCAM.com. Product(s) purchased from other sellers or sources are not covered by this Limited Warranty. YDS guarantees that the Product(s) will be free from defects in materials and workmanship under normal use for a period of one (1) year from the date you receive the product ("Warranty Period").

For all Product(s) that contain or develop material defects in materials or workmanship during the Warranty Period, YDS will, at its sole option, either: (i) repair the Product(s); (ii) replace the Product(s) with a new or refurbished Product(s) (replacement Product(s) being of identical model or functional equivalent); or (iii) provide you a refund of the price you paid for the Product(s).

This Limited Warranty of YDS is solely limited to repair and/or replacement on the terms set forth above. YDS is not reliable or responsible for any subsequential events.

YDS Strength

Powerful Factory

Professional Service

Promised Delivery